Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-04
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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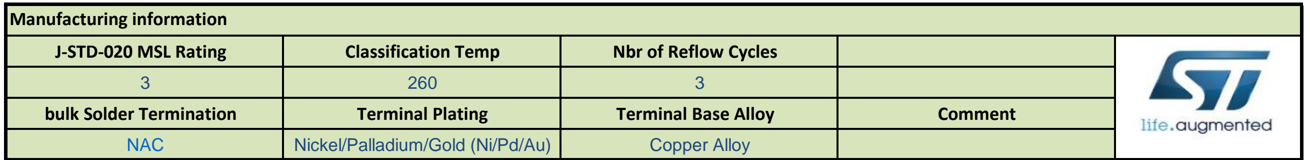
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F756VGT6	P01L*449XXXZ	A	9998	2018-03-04
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	681.44	mg	Each	ECOPACK® 2
,	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	14x14x1.4	100	L Bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-12th January 2017	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**TRUE**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**P01L*449XXXZ**				6000000.0	0.0
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	24.764	mg	supplier	die	Silicon (Si)	7440-21-3		23.516	mg	949604	34509
				supplier	metallization	Aluminium (Al)	7429-90-5		0.087	mg	3513	128
				supplier	metallization	Copper (Cu)	7440-50-8		0.567	mg	22896	832
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	81	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.079	mg	3190	116
				supplier	metallization	Tungsten (W)	7440-33-7		0.255	mg	10297	374
				supplier	Passivation	Silicon Nitride	12033-89-5		0.066	mg	2665	97
				supplier	Passivation	Silicon Oxide	7631-86-9		0.192	mg	7753	282
LEADFRAME (HDS- C194 uPPF)	M-011 Other inorganic materials	157.546	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		153.529	mg	974503	225301
				supplier	ALLOY	Iron (Fe)	7439-89-6		3.781	mg	23999	5549
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.189	mg	1200	277
				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.047	mg	298	69
LEADFRAME (HDS - PPF)	M-011 Other inorganic materials	5.330	mg	supplier	COATING	Nickel (Ni)	7440-02-0		5.170	mg	969981	7587
				supplier	COATING	Palladium (Pd)	7440-05-3		0.110	mg	20638	161
				supplier	COATING	Gold (Au)	7440-57-5		0.050	mg	9381	73
DIE ATTACH (Sumitomo - CRM - 1076	M-011 Other inorganic materials	2.992	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.150	mg	50134	220
				supplier	GLUE	Epoxy resin B	Proprietary		0.404	mg	135027	593
				supplier	GLUE	Silver(Ag)	7440-22-4		2.094	mg	699866	3073
				supplier	GLUE	Silica	Proprietary		0.299	mg	99933	439
				supplier	GLUE	Hardener	Proprietary		0.045	mg	15040	66
BONDING WIRE (MKE - HTS Au wire)	M-011 Other inorganic materials	1.534	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.533	mg	999348	2250
				supplier	BONDING WIRE	Palladium (Pd)	7440-41-7		0.001	mg	652	1
ENCAPSULATION (Sumitomo -G631H(	M-011 Other inorganic materials	489.274	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		49.052	mg	100255	71983
				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		410.790	mg	839591	-397174
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		2.453	mg	5014	3600
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		26.979	mg	55141	39591